

Nomenclature Guide

Intersil Nomenclatures

ISL Types

| PREFIX | ISL | X | XXXX | X | I | XX | X | XXX | Z | -T | SUFFIX/ POST PROCESSING/ SPECIAL SERVICES |
|---|-----|---|------|---|---|----|---|-----|---|----|---|
| FAMILY DESIGNATOR | | | | | | | | | | | |
| 1: DSL, RTC, Clocks, ATE, Energy LED Lighting 2: Reference, DCPs, Buffers, Sensors, Precision Op Amp, Precision ADC & DAC 3: Interface, Data Communication 4: Analog Component Solutions 5: High Speed Amps, Switch/MUX, ADCs, DACs, Optical, Video, Telecom VoIP, DSP Function Specific 6: Desktop Power 7: Space, Auto 8: Analog Switches, General Purpose Power 9: Notebook, Handheld A: High Speed ADCs | | | | | | | | | | | |
| PART NUMBER | | | | | | | | | | | |
| 3 to 5 Digits | | | | | | | | | | | |
| OPTION | | | | | | | | | | | |
| E: 15kV ESD Protected DCP Resistance Options W: 10k U: 50k T: 100k | | | | | | | | | | | |
| TEMPERATURE RANGE | | | | | | | | | | | |
| C: 0°C to +70°C (Commercial) D: 0°C to +85°C H: -10°C to +100°C (Hi-Temp Comm.) E: -20°C to +85°C (Extended Comm.) I: -40°C to +85°C (Industrial) A: -40°C to +105°C (Automotive) F: -40°C to +125°C (Full-range Industrial) P: -40°C to +130°C (Power Supply) M: -55°C to +125°C (Military) RHV: QML Class V (Radiation Hardened) RHQ: QML Class Q (Radiation Hardened) RHT: QML Class T (Radiation Hardened) EHV: QML Class V (Radiation Hardened) EHQ: QML Class Q (Radiation Hardened) EHT: QML Class T (Radiation Hardened) | | | | | | | | | | | |
| PB-FREE OPTION | | | | | | | | | | | |
| Z: ROHS and IEC61249-2-21 Halogen Free | | | | | | | | | | | |
| SPECIAL SELECTIONS | | | | | | | | | | | |
| Optional Characters to Denote Operating Conditions or Package Options: 18: 1.8V 33: 3.3V EP: Enhanced Product (DSCC Vendor Item Drawing) EPZ: Enhanced Product w/100% Matte Tin Lead Finish A, B etc.: Firmware revision. This will not appear on part marking | | | | | | | | | | | |
| OPTIONAL ELECTRICAL GRADE | | | | | | | | | | | |
| To Denote Speed or Precision Grading as Defined in Datasheet | | | | | | | | | | | |
| PACKAGE DESIGNATOR | | | | | | | | | | | |
| A: Shrink Small Outline Plastic (SSOP/QSOP) B: Small Outline Plastic (SOIC) BE: Exposed Pad SOIC (EPSOIC) C: Available D: Ceramic Dual-In-Line Metal Seal (SBDIP) E: Small Outline Transistor Plastic (SC-70) F: Ceramic Flatpack FE: Ceramic Flatpack w/Heatsink G: Single In-line Plastic (SIP) TO-220 GS: Single In-line Plastic, Surface Mount (SIP) TO-263 H: Small Outline Transistor Plastic (SOT-23) HT: Thin Small Outline Transistor Plastic (TSOT) I: Chip Scale Package (CSP) J: Ceramic Dual-In-Line Frit Seal (CERDIP) K: Ball Grid Array (FBGA/PBGA/LGA) KE: Heat Sink Ball Grid Array (HBGA) KV: Very Thin Fine Pitch BGA (VFBGA) L: Ceramic Leadless Chip Carrier (CLCC, SMD 0.5) M: Plastic Leaded Chip Carrier (PLCC) N: Thin Plastic Quad Flatpack (TQFP/LQFP) NE: Thin Plastic Quad Flatpack (TQFP/LQFP w/Exposed Pad) O: Do Not Use P: Dual-In-Line Plastic (PDIP) Q: Metric Plastic Quad Flatpack (MQFP/PQFP) R: Quad/Dual Flat No Lead (QFN/DFN)/HDA (High Density Array) RA: Array Flat No Lead (AFN) RO: Optical Quad/Dual Flat No Lead (OQFN/ODFN) ROM: Optical Quad/Dual Flat No Lead Module RT: Thin Quad/Dual Flat No Lead (TQFN/TDFN) RU: Ultra Thin Quad/Dual Flat No Lead (UTQFN/UTDFN/ePad UTQFN) RS: Top Exposed Pad QFN (TEPQFN) RX: Extreme Thin Flat No Lead (X2DFN/X2QFN) S: Header (TO-257) T: Metal Can (TO-39) U: Mini Small Outline Package (MSOP) UE: Thermally Enhanced Mini Small Outline Package (HMSOP) UO: Optical Mini Small Outline Package (OSOP) V: THIN Shrink Small Outline Plastic (TSSOP) VE: Thermally Enhanced Thin Shrink Small Outline Plastic (HTSSOP/EPTSSOP) W: Wafer Sale WMB: Wafer Sale With Solderable Metal Backing Layer XM: Die Sale, Military Visual (Condition B) XC: Die Sale, Commercial Visual XB: Die Sale, Bumped Die (FCP) Y: Available Z: Do Not Use | | | | | | | | | | | |
| SUFFIX/ POST PROCESSING/ SPECIAL SERVICES | | | | | | | | | | | |
| -T: Tape and Reel -T1: Tape and Reel -T2: Tape and Reel w/Vacuum Pack -T7: 7" Reel -TS: 7" Reel, 100 pc. -T7A: 7" Reel, 250pc. -T13: 13" Reel -T5: 500pc Tape and Reel -TK: 1,000pc Tape and Reel -T5K: 5,000pc Tape and Reel -EV: Evaluation Board -EVZ: Evaluation Board ROHS Compliant -DM: Demo Board -DMZ: Demo Board ROHS Compliant -RF: Ref Design Eval Board -RFZ: Ref Design Eval Board ROHS Compliant -EC: Enhanced Commercial (Enhanced EOL, MIL-PRF-38535 Change Notice, Traceable to Wafer Lot) | | | | | | | | | | | |